

• General Description

The ZMP68304U combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. Two P Channel MOSFET inside for dual DIE implication.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Dual DIE in one package

• Application

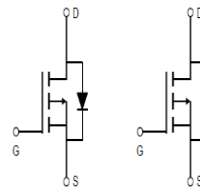
- Power Management in Notebook Computer
- BLDC Motor driver

• Ordering Information:

Part NO.	ZMP68304U
Marking	68304
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• P Channel Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	$I_{D@TC=25^\circ\text{C}}$	-1.5	A
	$I_{D@TC=75^\circ\text{C}}$	-1.1	A
	$I_{D@TC=100^\circ\text{C}}$	-0.9	A
Pulsed Drain Current ^①	I_{DM}	-4.5	A
Total Power Dissipation($TC=25^\circ\text{C}$)	$P_D@TC=25^\circ\text{C}$	3.0	W
Total Power Dissipation($TA=25^\circ\text{C}$)	$P_D@TA=25^\circ\text{C}$	0.6	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

• Product Summary


$V_{DS1} = -30\text{V}$
 $V_{DS2} = -30\text{V}$
 $R_{DS(ON)1} = 75\text{m}\Omega$
 $R_{DS(ON)2} = 75\text{m}\Omega$
 $I_{D1} = -1.5\text{A}$
 $I_{D2} = -1.5\text{A}$

D2 S2 D1



G2 S1 G1

SOT23-6



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	34	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	180	° C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu A$	-0.5		-1.2	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = -30V, V_{GS} = 0V$			-1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = -4.5V, I_D = -1.5A$		75	90	$m\Omega$
		$V_{GS} = -2.5V, I_D = -1A$		100	130	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = -10V, I_D = -0.5A$		1		s
Source-drain voltage	V_{SD}	$I_S = -1.5A$			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$f = 1MHz$	-	365	-	pF
Output capacitance	C_{oss}		-	67	-	
Reverse transfer capacitance	C_{rss}		-	33	-	

•Gate Charge characteristics($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD} = 25V$	-	3.8	-	nC
Gate - Source charge	Q_{gs}	$I_D = -4A$	-	1.2	-	
Gate - Drain charge	Q_{gd}	$V_{GS} = 10V$	-	1.9	-	

•P Channel characteristics curve

Fig.1 Power Dissipation Derating Curve

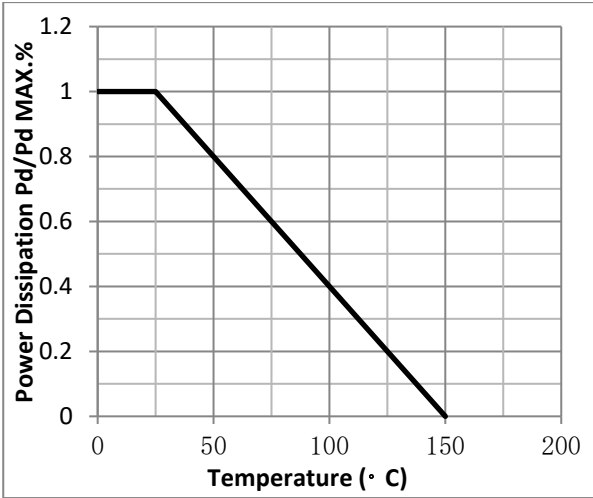


Fig.2 Typical output Characteristics

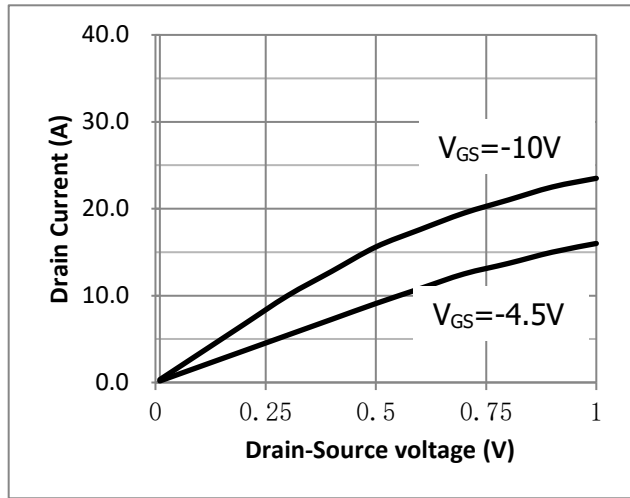


Fig.3 Threshold Voltage V.S Junction Temperature

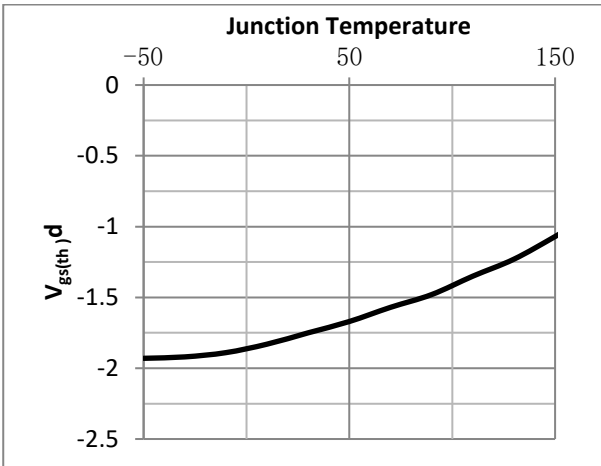


Fig.4 Resistance V.S Drain Current

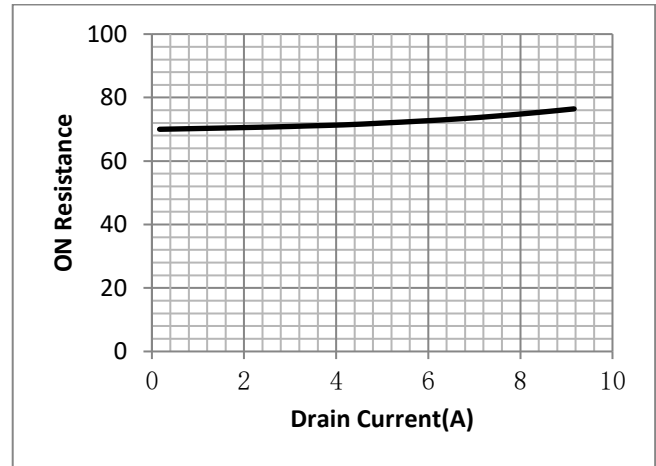


Fig.5 On-Resistance VS Gate Source Voltage

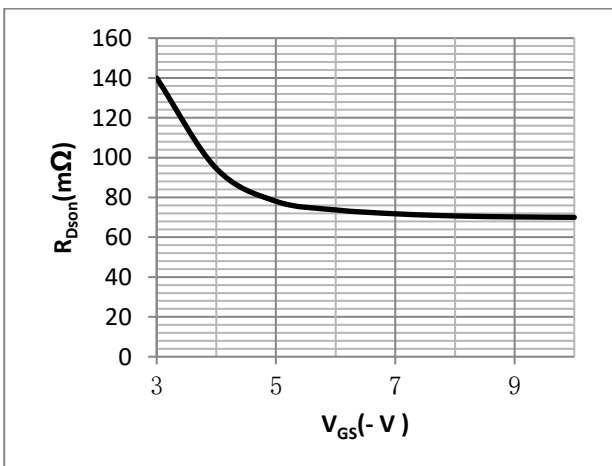
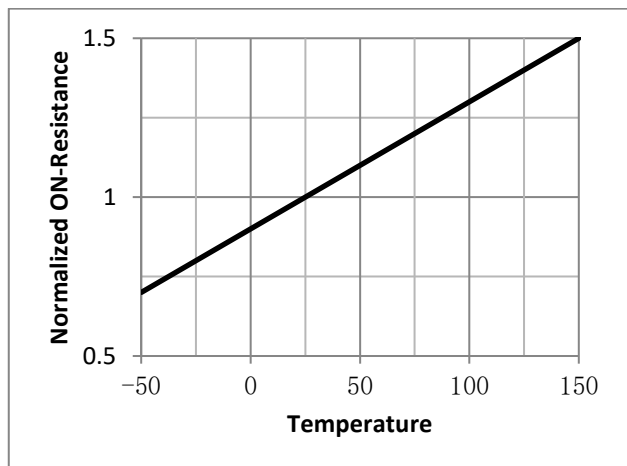


Fig.6 On-Resistance V.S Junction Temperature



• Test Circuit

Fig.7 Switching Time Measurement Circuit

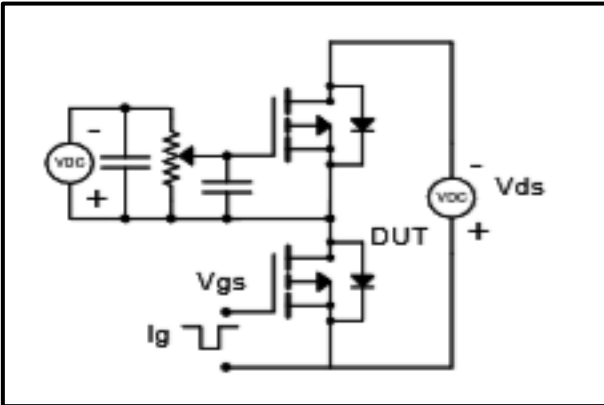


Fig.8 Gate Charge Waveform

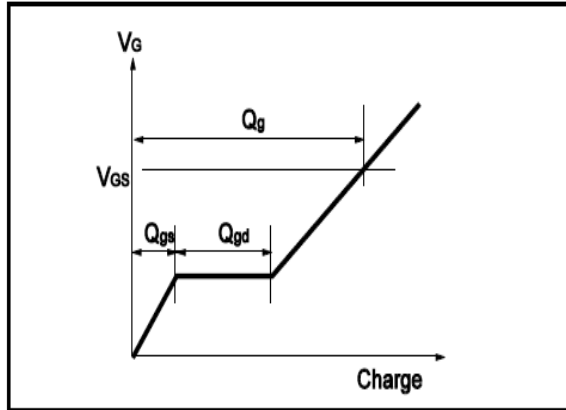


Fig.9 Switching Time Measurement Circuit

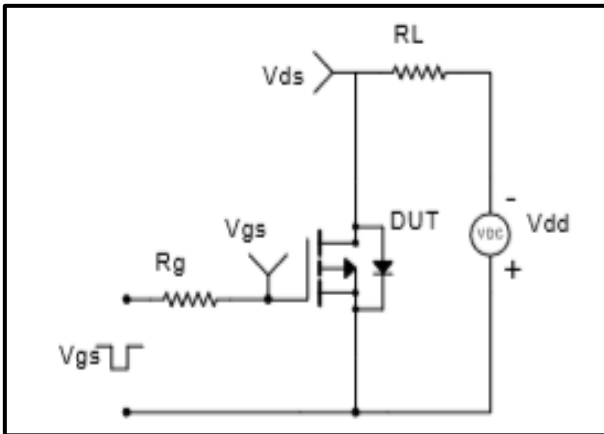


Fig.10 Gate Charge Waveform

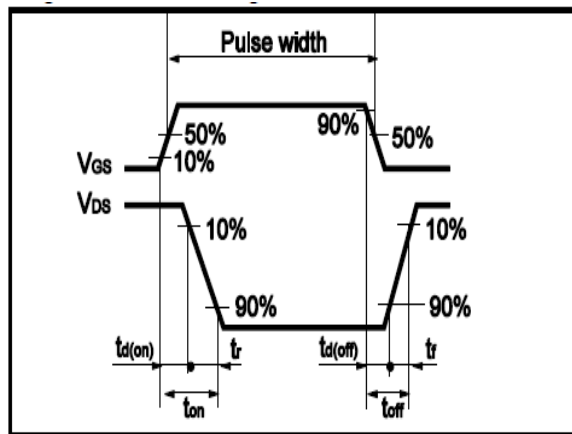


Fig.11 Avalanche Measurement Circuit

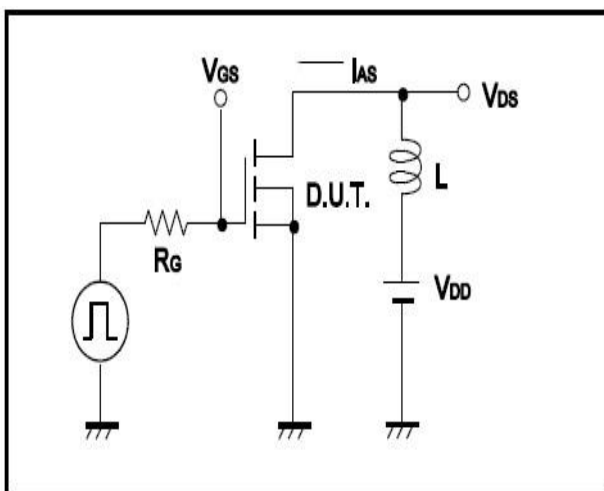
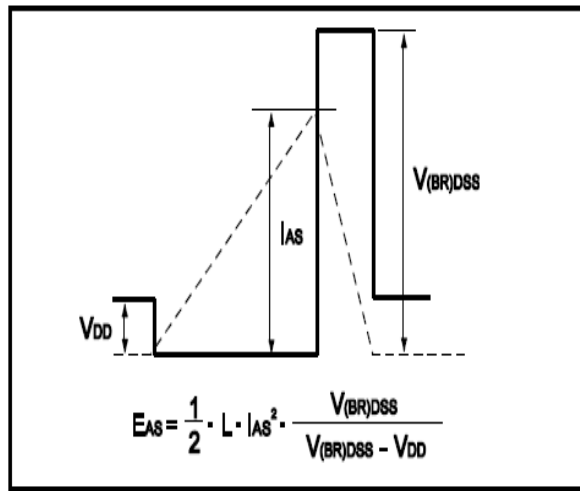


Fig.12 Avalanche Waveform



•Dimensions(SOT23-6)

